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VLSI-SoC: Design and Engineering of Electronics Systems Based on New Computing Paradigms

Nicola Bombieri, Graziano Pravadelli, Masahiro Fujita, Todd Austin, Ricardo Reis

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Nicola Bombieri · Graziano Pravadelli ·
Masahiro Fujita · Todd Austin ·
Ricardo Reis (Eds.)

VLSI-SoC: Design and Engineering of Electronics Systems Based on New Computing Paradigms

26th IFIP WG 10.5/IEEE International Conference
on Very Large Scale Integration, VLSI-SoC 2018
Verona, Italy, October 8–10, 2018
Revised and Extended Selected Papers

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Preface

This book contains extended and revised versions of the highest-quality papers presented during the 26th edition of the IFIP/IEEE WG10.5 International Conference on Very Large Scale Integration (VLSI-SoC), a global System-on-Chip Design and CAD conference. The 26th edition of the conference was held during October 8–10, 2018, at the Hotel Leon d’Oro, Verona, Italy. Previous conferences have taken place in Edinburgh, Scotland (1981); Trondheim, Norway (1983); Tokyo, Japan (1985); Vancouver, Canada (1987); Munich, Germany (1989); Edinburgh, Scotland (1991); Grenoble, France (1993); Chiba, Japan (1995); Gramado, Brazil (1997); Lisbon, Portugal (1999); Montpellier, France (2001); Darmstadt, Germany (2003); Perth, Australia (2005); Nice, France (2006); Atlanta, GA, USA (2007); Rhodes Island, Greece (2008); Florianopolis, Brazil (2009); Madrid, Spain (2010); Kowloon, Hong Kong, SAR China (2011), Santa Cruz, CA, USA (2012), Istanbul, Turkey (2013), Playa del Carmen, Mexico (2014), Daejeon, South Korea (2015), Tallin, Estonia (2016), and Abu Dhabi, United Arab Emirates (2017).

The purpose of this conference, sponsored by IFIP TC 10 Working Group 10.5, the IEEE Council on Electronic Design Automation (CEDA), and the IEEE Circuits and Systems Society, with the In-Cooperation of ACM SIGDA, is to provide a forum for the presentation and discussion of the latest academic and industrial results and developments as well as the future trends in the field of system-on-chip (SoC) design, considering the challenges of nano-scale, state-of-the-art and emerging manufacturing technologies. In particular, VLSI-SoC 2018 was held under the theme “Design and Engineering of Electronics Systems Based on New Computing Paradigms” by addressing cutting-edge research fields like heterogeneous, neuromorphic, and brain-inspired, biologically inspired, approximate computing systems. The chapters of this new book in the VLSI-SoC series continue its tradition of providing an internationally acknowledged platform for scientific contributions and industrial progress in this field.

For VLSI-SoC 2018, 27 papers out of 106 submissions were selected for presentation, and out of these 27 full papers presented at the conference, 13 papers were chosen by a special selection committee to have an extended and revised version included in this book. The selection process of these papers considered the evaluation scores during the review process as well as the review forms provided by members of the Technical Program Committee and the Session Chairs as a result of the presentations.

The chapters of this book have authors from Germany, India, Italy, Japan, Mexico, Singapore, The Netherlands, UAE, and USA. The Technical Program Committee for the regular tracks comprised 98 members from 25 countries.

VLSI-SoC 2018 was the culmination of the work of many dedicated volunteers: paper authors, reviewers, session chairs, invited speakers, and various committee chairs. We thank them all for their contributions.

This book is intended for the VLSI community at large, and in particular the many colleagues who did not have the chance to attend the conference. We hope you will enjoy reading this book and that you will find it useful in your professional life and for the development of the VLSI community as a whole.

June 2019

Nicola Bombieri
Graziano Pravadelli
Masahiro Fujita
Todd Austin
Ricardo Reis

Organization

The IFIP/IEEE International Conference on Very Large Scale Integration System-on-Chip (VLSI-SoC) 2018 took place during October 8–10, 2018, at the Hotel Leon d’Oro, Verona, Italy. VLSI-SoC 2018 was the 26th in a series of international conferences, sponsored by IFIP TC 10 Working Group 10.5 (VLSI), IEEE CEDA and ACM SIGDA.

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Contents

A 65 nm CMOS Synthesizable Digital Low-Dropout Regulator Based on Voltage-to-Time Conversion with 99.6% Current Efficiency at 10-mA Load	1
<i>Naoki Ojima, Toru Nakura, Tetsuya Iizuka, and Kunihiro Asada</i>	
An Instruction Set Architecture for Secure, Low-Power, Dynamic IoT Communication.	14
<i>Shahzad Muzaffar and Ibrahim (Abe) M. Elfadel</i>	
The Connection Layout in a Lattice of Four-Terminal Switches	32
<i>Anna Bernasconi, Antonio Boffa, Fabrizio Luccio, and Linda Pagli</i>	
Building High-Performance, Easy-to-Use Polymorphic Parallel Memories with HLS.	53
<i>L. Stornaiuolo, M. Rabozzi, M. D. Santambrogio, D. Sciuto, C. B. Ciobanu, G. Stramondo, and A. L. Varbanescu</i>	
Rectification of Arithmetic Circuits with Craig Interpolants in Finite Fields	79
<i>Utkarsh Gupta, Irina Iliaeva, Vikas Rao, Arpitha Srinath, Priyank Kalla, and Florian Enescu</i>	
Energy-Accuracy Scalable Deep Convolutional Neural Networks: A Pareto Analysis	107
<i>Valentino Peluso and Andrea Calimera</i>	
ReRAM Based In-Memory Computation of Single Bit Error Correcting BCH Code	128
<i>Swagata Mandal, Yaswanth Tavva, Debjyoti Bhattacharjee, and Anupam Chattopadhyay</i>	
Optimizing Performance and Energy Overheads Due to Fanout in In-Memory Computing Systems	147
<i>Md Adnan Zaman, Rajeev Joshi, and Srinivas Katkoori</i>	
Mapping Spiking Neural Networks on Multi-core Neuromorphic Platforms: Problem Formulation and Performance Analysis	167
<i>Francesco Barchi, Gianvito Urgese, Enrico Macii, and Andrea Acquaviva</i>	
Improved Test Solutions for COTS-Based Systems in Space Applications . . .	187
<i>Riccardo Cantoro, Sara Carbonara, Andrea Florida, Ernesto Sanchez, Matteo Sonza Reorda, and Jan-Gerd Mess</i>	

Analysis of Bridge Defects in STT-MRAM Cells Under Process Variations and a Robust DFT Technique for Their Detection 207
Victor Champac, Andres Gomez, Freddy Forero, and Kaushik Roy

Assessment of Low-Budget Targeted Cyberattacks Against Power Systems 232
XiaoRui Liu, Anastasis Keliris, Charalambos Konstantinou, Marios Sazos, and Michail Maniatakos

Efficient Hardware/Software Co-design for NTRU 257
Tim Fritzmann, Thomas Schamberger, Christoph Frisch, Konstantin Braun, Georg Maringer, and Johanna Sepúlveda

Author Index 281